



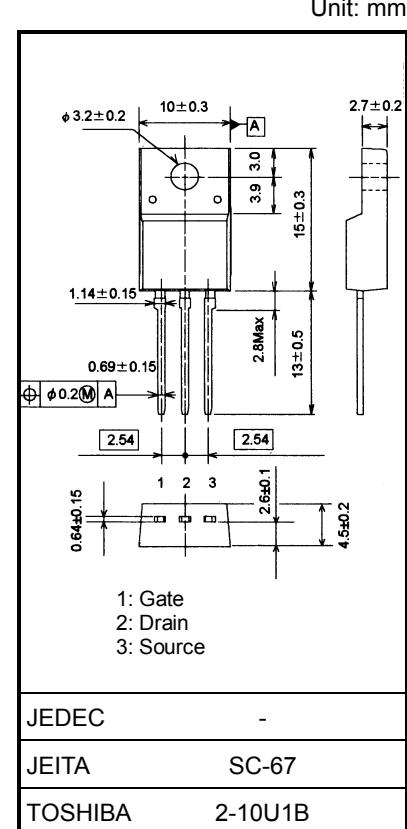
TK80A08K3

Switching Regulator Applications

- Low drain-source ON-resistance: $R_{DS(ON)} = 3.6 \text{ m}\Omega$ (typ.)
- High forward transfer admittance: $|Y_{fs}| = 200 \text{ S}$
- Low leakage current: $I_{DSS} = 10 \mu\text{A}$ (max) ($V_{DS} = 75 \text{ V}$)
- Enhancement mode: $V_{th} = 2.0$ to 4.0 V ($V_{DS} = 10 \text{ V}$, $I_D = 1 \text{ mA}$)

Absolute Maximum Ratings ($T_a = 25^\circ\text{C}$)

Characteristics		Symbol	Rating	Unit
Drain-source voltage		V_{DSS}	75	V
Drain-gate voltage ($R_{GS} = 20 \text{ k}\Omega$)		V_{DGR}	75	V
Gate-source voltage		V_{GSS}	± 20	V
Drain current	DC (Note 1)	I_D	80	A
	Pulse (Note 1)	I_{DP}	320	
Drain power dissipation ($T_c = 25^\circ\text{C}$)		P_D	40	W
Single pulse avalanche energy (Note 2)		E_{AS}	443	mJ
Avalanche current		I_{AR}	80	A
Repetitive avalanche energy (Note 3)		E_{AR}	4	mJ
Channel temperature		T_{ch}	150	°C
Storage temperature range		T_{stg}	-55 to 150	°C



Weight: 1.7 g (typ.)

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	$R_{th}(\text{ch-c})$	3.125	°C/W
Thermal resistance, channel to ambient	$R_{th}(\text{ch-a})$	62.5	°C/W

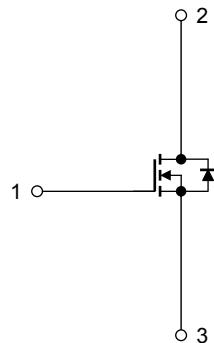
Note 1: Ensure that the channel and lead temperatures do not exceed 150°C.

Note 2: $V_{DD} = 25 \text{ V}$, $T_{ch} = 25^\circ\text{C}$, $L = 100 \mu\text{H}$, $I_{AR} = 80 \text{ A}$, $R_G = 1 \Omega$

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Handle with care.

Internal Connection



Electrical Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit	
Gate leakage current	I _{GSS}	V _{GS} = ±20 V, V _{DS} = 0 V	—	—	±1	µA	
Drain cut-OFF current	I _{DSS}	V _{DS} = 75 V, V _{GS} = 0 V	—	—	10	µA	
Drain-source breakdown voltage	V _{(BR) DSS}	I _D = 10 mA, V _{GS} = 0 V	75	—	—	V	
	V _{(BR) DSX}	I _D = 10 mA, V _{GS} = -20 V	55	—	—		
Gate threshold voltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	—	4.0	V	
Drain-source ON-resistance (Note 4)	R _{DSON}	V _{GS} = 10 V, I _D = 40 A	—	3.6	4.5	mΩ	
Forward transfer admittance	Y _{fs}	V _{DS} = 10 V, I _D = 40 A	100	200	—	S	
Input capacitance	C _{iss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	—	8200	—	pF	
Reverse transfer capacitance	C _{rss}		—	770	—		
Output capacitance	C _{oss}		—	1140	—		
Switching time	Rise time	t _r	 V _{GS} 10 V 0 V I _D = 40 A R _L = 0.75 Ω V _{DD} ≈ 30 V Duty ≤ 1%, t _w = 10 µs	—	30	—	ns
	Turn-ON time	t _{on}		—	55	—	
	Fall time	t _f		—	33	—	
	Turn-OFF time	t _{off}		—	150	—	
Total gate charge (gate-source plus gate-drain)	Q _g	 V _{DD} ≈ 60 V, V _{GS} = 10 V, I _D = 80 A	—	175	—	nC	
Gate-source charge 1	Q _{gs1}		—	40	—		
Gate-drain ("miller") charge	Q _{gd}		—	65	—		
Gate switch charge	Q _{sw}		—	80	—		

Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	—	—	—	80	A
Pulse drain reverse current (Note 1)	I _{DRP}	—	—	—	320	A
Forward voltage (diode)	V _{DSF}	I _{DR} = 80 A, V _{GS} = 0 V	—	-0.9	-1.2	V
Reverse recovery time	t _{rr}	I _{DR} = 80 A, V _{GS} = 0 V,	—	60	—	ns
Reverse recovery charge	Q _{rr}	dI _{DR} /dt = 50 A/µs	—	60	—	nC

Marking